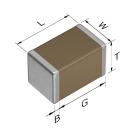
积层贴片陶瓷片式电容器

C2012X5R2E332M085AA

RoHS Reach Halogen Free Pb Free

交货型号	C2012X5R2E332MT****
用途	一般等级
特点	Mid 中耐压(100~630V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸		
长度(L)	2.00mm ±0.20mm	
宽度(W)	1.25mm ±0.20mm	
厚度(T)	$0.85 \text{mm} \pm 0.15 \text{mm}$	
端子宽度(B)	0.20mm Min.	
端子间隔(G)	0.50mm Min.	
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)	
J世行。序盆作/四(t n)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
J世行。拜益州/四(t D)	0.70mm to 0.90mm (Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
]此行/开血。印/四 (t C/	0.90mm to 1.20mm(Reflow Soldering)	

电气特性		
电容	3. $3nF \pm 20\%$	
额定电压	250VDC	
温度特性	$X5R(\pm 15\%)$	
耗散因数(Max.)	3%	
绝缘电阻 (Min.)	10000M Ω	

	其他
焊接方法	流体
年按月 伍	回流
AEC-Q200	NO NO
包装形式	纸编带 (180mm卷筒)
包装个数	4000pcs

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

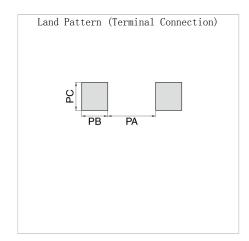
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Associated Images



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